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Details	
Product Status	Obsolete
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	-
Peripherals	LVD, POR, PWM
Number of I/O	5
Program Memory Size	4KB (4K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	8-SOIC (0.209", 5.30mm Width)
Supplier Device Package	8-SO
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mchc908qt4vdwe



MC68HC908QY4 MC68HC908QY2 MC68HC908QY2 MC68HC908QY1 MC68HC908QY1 MC68HC908QT1

Data Sheet

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MC68HC908QY/QT Family Data Sheet, Rev. 6



1.6 Pin Function Priority

Table 1-3 is meant to resolve the priority if multiple functions are enabled on a single pin.

NOTE

Upon reset all pins come up as input ports regardless of the priority table.

Table 1-3. Function Priority in Shared Pins

Pin Name	Highest-to-Lowest Priority Sequence
PTA0	$AD0 \rightarrow TCH0 \rightarrow KBI0 \rightarrow PTA0$
PTA1	AD1 \rightarrow TCH1 \rightarrow KBI1 \rightarrow PTA1
PTA2	$\overline{\text{IRQ}} \rightarrow \text{KBI2} \rightarrow \text{TCLK} \rightarrow \text{PTA2}$
PTA3	$\overline{RST} \to KBI3 \to PTA3$
PTA4	$OSC2 \rightarrow AD2 \rightarrow KBI4 \rightarrow PTA4$
PTA5	$OSC1 \to AD3 \to KBI5 \to PTA5$



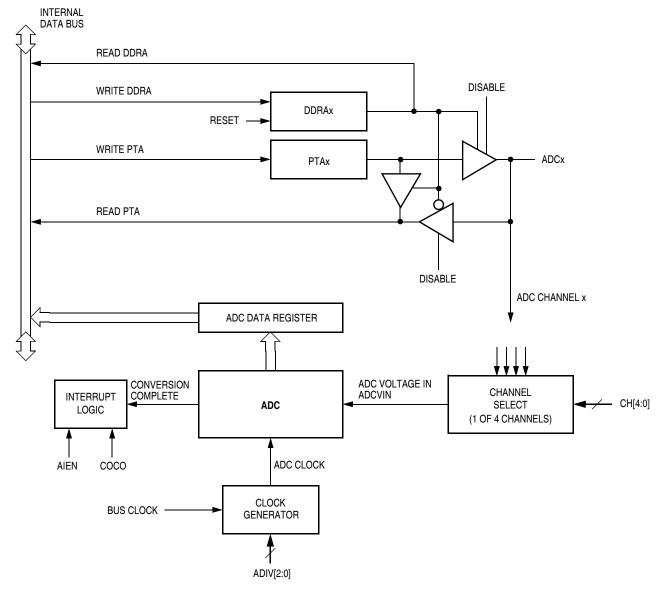


Figure 3-2. ADC Block Diagram



Analog-to-Digital Converter (ADC)



Computer Operating Properly (COP)

The COP counter is a free-running 6-bit counter preceded by the 12-bit system integration module (SIM) counter. If not cleared by software, the COP counter overflows and generates an asynchronous reset after 262,128 or 8176 BUSCLKX4 cycles; depending on the state of the COP rate select bit, COPRS, in configuration register 1. With a 262,128 BUSCLKX4 cycle overflow option, the internal 12.8-MHz oscillator gives a COP timeout period of 20.48 ms. Writing any value to location \$FFFF before an overflow occurs prevents a COP reset by clearing the COP counter and stages 12–5 of the SIM counter.

NOTE

Service the COP immediately after reset and before entering or after exiting stop mode to guarantee the maximum time before the first COP counter overflow.

A COP reset pulls the \overline{RST} pin low (if the RSTEN bit is set in the CONFIG1 register) for $32 \times BUSCLKX4$ cycles and sets the COP bit in the reset status register (RSR). See 13.8.1 SIM Reset Status Register.

NOTE

Place COP clearing instructions in the main program and not in an interrupt subroutine. Such an interrupt subroutine could keep the COP from generating a reset even while the main program is not working properly.

6.3 I/O Signals

The following paragraphs describe the signals shown in Figure 6-1.

6.3.1 BUSCLKX4

BUSCLKX4 is the oscillator output signal. BUSCLKX4 frequency is equal to the internal oscillator frequency, the crystal frequency, or the RC-oscillator frequency.

6.3.2 STOP Instruction

The STOP instruction clears the SIM counter.

6.3.3 COPCTL Write

Writing any value to the COP control register (COPCTL) (see 6.4 COP Control Register) clears the COP counter and clears stages 12–5 of the SIM counter. Reading the COP control register returns the low byte of the reset vector.

6.3.4 Power-On Reset

The power-on reset (POR) circuit in the SIM clears the SIM counter $4096 \times BUSCLKX4$ cycles after power up.

6.3.5 Internal Reset

An internal reset clears the SIM counter and the COP counter.

6.3.6 COPD (COP Disable)

The COPD signal reflects the state of the COP disable bit (COPD) in the configuration register 1 (CONFIG1). See Chapter 5 Configuration Register (CONFIG).

MC68HC908QY/QT Family Data Sheet, Rev. 6



Central Processor Unit (CPU)

7.7 Instruction Set Summary

Table 7-1 provides a summary of the M68HC08 instruction set.

Table 7-1. Instruction Set Summary (Sheet 1 of 6)

Source	Operation Description							Effect on CCR				Address Mode	Opcode	Operand	les
Form	o polition	2000.1011011	٧	Н	I	N	z	С	Add	Opc	Ope	Cycles			
ADC #opr ADC opr ADC opr ADC opr,X ADC opr,X ADC, X ADC opr,SP ADC opr,SP	Add with Carry	$A \leftarrow (A) + (M) + (C)$	1	‡	ı	‡	‡	‡	IMM DIR EXT IX2 IX1 IX SP1 SP2	A9 B9 C9 D9 E9 F9 9EE9 9ED9	ii dd hh II ee ff ff ee ff	2 3 4 4 3 2 4 5			
ADD #opr ADD opr ADD opr,X ADD opr,X ADD opr,X ADD opr,SP ADD opr,SP	Add without Carry	A ← (A) + (M)	‡	‡	-	1	1	‡	IMM DIR EXT IX2 IX1 IX SP1 SP2	AB BB CB DB EB FB 9EEB 9EDB		2 3 4 4 3 2 4 5			
AIS #opr	Add Immediate Value (Signed) to SP	SP ← (SP) + (16 « M)	-	_	_	_	_	-	IMM	A7	ii	2			
AIX #opr	Add Immediate Value (Signed) to H:X	H:X ← (H:X) + (16 ≪ M)	-	_	_	_	-	-	IMM	AF	ii	2			
AND #opr AND opr AND opr, AND opr,X AND opr,X AND, X AND opr,SP AND opr,SP	Logical AND	A ← (A) & (M)	0	_	_	‡	‡	_	IMM DIR EXT IX2 IX1 IX SP1 SP2	A4 B4 C4 D4 E4 F4 9EE4 9ED4	ii dd hh II ee ff ff ff ee ff	2 3 4 4 3 2 4 5			
ASL opr ASLA ASLX ASL opr,X ASL ,X ASL ,Opr,SP	Arithmetic Shift Left (Same as LSL)	C → 0 b0	1	_	-	‡	1	‡	DIR INH INH IX1 IX SP1	38 48 58 68 78 9E68	dd ff ff	4 1 1 4 3 5			
ASR opr ASRA ASRX ASR opr,X ASR opr,X ASR opr,SP	Arithmetic Shift Right	b7 b0	ţ	_	-	‡	ţ	‡	DIR INH INH IX1 IX SP1	37 47 57 67 77 9E67	dd ff ff	4 1 1 4 3 5			
BCC rel	Branch if Carry Bit Clear	$PC \leftarrow (PC) + 2 + rel ? (C) = 0$	_	_	_	_	-	-	REL	24	rr	3			
BCLR n, opr	Clear Bit n in M	Mn ← 0	_	_	_	_	_	_	DIR (b0) DIR (b1) DIR (b2) DIR (b3) DIR (b4) DIR (b5) DIR (b6) DIR (b7)	11 13 15 17 19 1B 1D 1F	dd dd dd dd dd dd dd dd	4 4 4 4 4 4 4			
BCS rel	Branch if Carry Bit Set (Same as BLO)	PC ← (PC) + 2 + rel? (C) = 1	-	-	-	_	-	-	REL	25	rr	3			
BEQ rel	Branch if Equal	$PC \leftarrow (PC) + 2 + rel? (Z) = 1$	_	_	_	_	-	-	REL	27	rr	3			
BGE opr	Branch if Greater Than or Equal To (Signed Operands)	$PC \leftarrow (PC) + 2 + rel? (N \oplus V) = 0$	_	-	_	_	_	_	REL	90	rr	3			
BGT opr	Branch if Greater Than (Signed Operands)	$PC \leftarrow (PC) + 2 + rel?(Z) \mid (N \oplus V) = 0$	_	-	-	_	-	-	REL	92	rr	3			
BHCC rel	Branch if Half Carry Bit Clear	$PC \leftarrow (PC) + 2 + rel? (H) = 0$	_	_	_	_	_	_	REL	28	rr	3			
BHCS rel	Branch if Half Carry Bit Set	PC ← (PC) + 2 + rel? (H) = 1	<u> -</u>	_	_	_	_	_	REL	29	rr	3			
BHI rel	Branch if Higher	$PC \leftarrow (PC) + 2 + rel? (C) (Z) = 0$	-	-	_	_	_	-	REL	22	rr	3			

MC68HC908QY/QT Family Data Sheet, Rev. 6



Central Processor Unit (CPU)

Table 7-1. Instruction Set Summary (Sheet 3 of 6)

Source	Operation	Description			Effect on CCR				Address Mode	Opcode	Operand	les
Form	• poration	2000 i piloti	٧	Н	I	N	Z	С	Add Mod	Opc	Ope	Cycles
CLI	Clear Interrupt Mask	I ← 0	_	-	0	-	-	-	INH	9A		2
CLR opr CLRA CLRX CLRH CLR opr,X CLR ,X CLR opr,SP	Clear	$\begin{array}{l} M \leftarrow \$00 \\ A \leftarrow \$00 \\ X \leftarrow \$00 \\ H \leftarrow \$00 \\ M \leftarrow \$00 \\ M \leftarrow \$00 \\ M \leftarrow \$00 \\ M \leftarrow \$00 \\ \end{array}$		-	_	0	1	_	DIR INH INH INH IX1 IX SP1	3F 4F 5F 8C 6F 7F 9E6F	ff ff	3 1 1 3 2 4
CMP #opr CMP opr CMP opr, CMP opr,X CMP opr,X CMP,X CMP opr,SP CMP opr,SP	Compare A with M	(A) – (M)		1		‡	1	‡	IMM DIR EXT IX2 IX1 IX SP1 SP2	A1 B1 C1 D1 E1 F1 9EE1 9ED1	ii dd hh II ee ff ff ff ee ff	2 3 4 4 3 2 4 5
COM opr COMA COMX COM opr,X COM ,X COM opr,SP	Complement (One's Complement)	$\begin{array}{l} M \leftarrow (\overline{M}) = \$FF - (M) \\ A \leftarrow (\overline{A}) = \$FF - (M) \\ X \leftarrow (X) = \$FF - (M) \\ M \leftarrow (\overline{M}) = \$FF - (M) \end{array}$	0	_	_	1	‡	1	DIR INH INH IX1 IX SP1	33 43 53 63 73 9E63	dd ff ff	4 1 1 4 3 5
CPHX #opr CPHX opr	Compare H:X with M	(H:X) – (M:M + 1)		-	_	1	1	1	IMM DIR	65 75	ii ii+1 dd	3 4
CPX #opr CPX opr CPX opr CPX ,X CPX opr,X CPX opr,X CPX opr,SP CPX opr,SP	Compare X with M	(X) – (M)	ţ	-	_	‡	1	‡	IMM DIR EXT IX2 IX1 IX SP1 SP2	A3 B3 C3 D3 E3 F3 9EE3 9ED3		23443245
DAA	Decimal Adjust A	(A) ₁₀	U	-	-	‡	1	1	INH	72		2
DBNZ opr,rel DBNZA rel DBNZX rel DBNZ opr,X,rel DBNZ X,rel DBNZ opr,SP,rel	Decrement and Branch if Not Zero	$\begin{array}{l} A \leftarrow (A) - 1 \text{ or } M \leftarrow (M) - 1 \text{ or } X \leftarrow (X) - 1 \\ PC \leftarrow (PC) + 3 + rel? \text{ (result)} \neq 0 \\ PC \leftarrow (PC) + 2 + rel? \text{ (result)} \neq 0 \\ PC \leftarrow (PC) + 2 + rel? \text{ (result)} \neq 0 \\ PC \leftarrow (PC) + 3 + rel? \text{ (result)} \neq 0 \\ PC \leftarrow (PC) + 2 + rel? \text{ (result)} \neq 0 \\ PC \leftarrow (PC) + 4 + rel? \text{ (result)} \neq 0 \\ PC \leftarrow (PC) + 4 + rel? \text{ (result)} \neq 0 \end{array}$	_	_	_	-	-	_	DIR INH INH IX1 IX SP1	3B 4B 5B 6B 7B 9E6B	dd rr rr rr ff rr rr ff rr	533546
DEC opr DECA DECX DEC opr,X DEC ,X DEC opr,SP	Decrement	$\begin{array}{l} M \leftarrow (M) - 1 \\ A \leftarrow (A) - 1 \\ X \leftarrow (X) - 1 \\ M \leftarrow (M) - 1 \\ M \leftarrow (M) - 1 \\ M \leftarrow (M) - 1 \end{array}$	Į.	_	_	1	1	-	DIR INH INH IX1 IX SP1	3A 4A 5A 6A 7A 9E6A	dd ff ff	4 1 1 4 3 5
DIV	Divide	A ← (H:A)/(X) H ← Remainder	_	_	_	-	1	1	INH	52		7
EOR #opr EOR opr EOR opr,X EOR opr,X EOR,X EOR,X EOR opr,SP EOR opr,SP	Exclusive OR M with A	$A \leftarrow (A \oplus M)$	0	_	_	1	1	_	IMM DIR EXT IX2 IX1 IX SP1 SP2	A8 B8 C8 D8 E8 F8 9EE8 9ED8	ii dd hh II ee ff ff ee ff	2 3 4 4 3 2 4 5
INC opr INCA INCX INC opr,X INC ,X INC opr,SP	Increment	$ \begin{array}{c} M \leftarrow (M) + 1 \\ A \leftarrow (A) + 1 \\ X \leftarrow (X) + 1 \\ M \leftarrow (M) + 1 \\ M \leftarrow (M) + 1 \\ M \leftarrow (M) + 1 \end{array} $	1	_	_	‡	†	_	DIR INH INH IX1 IX SP1	3C 4C 5C 6C 7C 9E6C	dd ff ff	4 1 1 4 3 5



Table 7-1. Instruction Set Summary (Sheet 6 of 6)

Source	Operation	Description		Description					Effect on CCR						Address Mode		Opcode	Operand	es
Form	- Cporanon	2000.ip.io.ii	٧	V H I N Z		Z	С	Add	Opc	Ope	Cycles								
SWI	Software Interrupt	$\begin{array}{c} PC \leftarrow (PC) + 1; Push (PCL) \\ SP \leftarrow (SP) - 1; Push (PCH) \\ SP \leftarrow (SP) - 1; Push (X) \\ SP \leftarrow (SP) - 1; Push (A) \\ SP \leftarrow (SP) - 1; Push (CCR) \\ SP \leftarrow (SP) - 1; I \leftarrow 1 \\ PCH \leftarrow Interrupt Vector High Byte \\ PCL \leftarrow Interrupt Vector Low Byte \\ \end{array}$		_	1	_	_	_	INH	83		9							
TAP	Transfer A to CCR	$CCR \leftarrow (A)$	‡	1	‡	‡	1	‡	INH	84		2							
TAX	Transfer A to X	X ← (A)	-	-	_	-	-	-	INH	97		1							
TPA	Transfer CCR to A	$A \leftarrow (CCR)$	-	-	_	-	-	-	INH	85		1							
TST opr TSTA TSTX TST opr,X TST ,X TST opr,SP	Test for Negative or Zero	(A) – \$00 or (X) – \$00 or (M) – \$00	0	-	_	ţ	ţ	_	DIR INH INH IX1 IX SP1	3D 4D 5D 6D 7D 9E6D	dd ff ff	3 1 1 3 2 4							
TSX	Transfer SP to H:X	H:X ← (SP) + 1	-	-	_	-	_	-	INH	95		2							
TXA	Transfer X to A	A ← (X)	-	-	_	-	_	-	INH	9F		1							
TXS	Transfer H:X to SP	(SP) ← (H:X) – 1	-	-	_	_	_	-	INH	94		2							
WAIT	Enable Interrupts; Wait for Interrupt	I bit ← 0; Inhibit CPU clocking until interrupted	-	-	0	-	_	_	INH	8F		1							

Α	Accumulator	n	Any bit
С	Carry/borrow bit	opr	Operand (one or two bytes)
CCR	Condition code register	PC	Program counter
dd	Direct address of operand	PCH	Program counter high byte
dd rr	Direct address of operand and relative offset of branch instruction	PCL	Program counter low byte
DD	Direct to direct addressing mode	REL	Relative addressing mode
DIR	Direct addressing mode	rel	Relative program counter offset byte
DIX+	Direct to indexed with post increment addressing mode	rr	Relative program counter offset byte
ee ff	High and low bytes of offset in indexed, 16-bit offset addressing	SP1	Stack pointer, 8-bit offset addressing mode
EXT	Extended addressing mode	SP2	Stack pointer 16-bit offset addressing mode
ff	Offset byte in indexed, 8-bit offset addressing	SP	Stack pointer
Н	Half-carry bit	U	Undefined
Н	Index register high byte	V	Overflow bit
hh II	High and low bytes of operand address in extended addressing	Χ	Index register low byte
	Interrupt mask	Z	Zero bit
ii	Immediate operand byte	&	Logical AND
IMD	Immediate source to direct destination addressing mode		Logical OR
IMM	Immediate addressing mode	\oplus	Logical EXCLUSIVE OR
INH	Inherent addressing mode	()	Contents of
IX	Indexed, no offset addressing mode	- ()	Negation (two's complement)
IX+	Indexed, no offset, post increment addressing mode	#	Immediate value
IX+D	Indexed with post increment to direct addressing mode	«	Sign extend
IX1	Indexed, 8-bit offset addressing mode	\leftarrow	Loaded with
IX1+	Indexed, 8-bit offset, post increment addressing mode	?	If
IX2	Indexed, 16-bit offset addressing mode	:	Concatenated with
M	Memory location	1	Set or cleared
N	Negative bit	_	Not affected

7.8 Opcode Map

See Table 7-2.



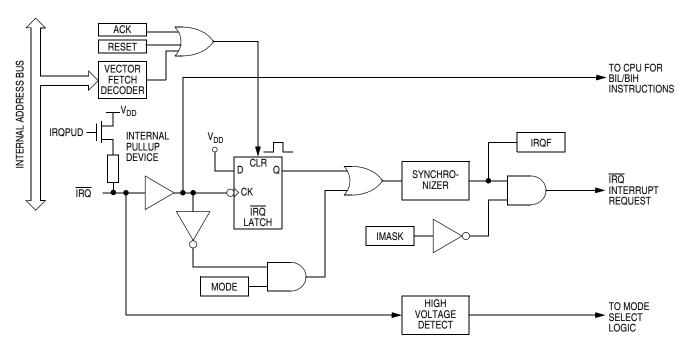


Figure 8-2. IRQ Module Block Diagram

8.3.1 MODE = 1

If the MODE bit is set, the \overline{IRQ} pin is both falling edge sensitive and low level sensitive. With MODE set, both of the following actions must occur to clear the \overline{IRQ} interrupt request:

- Return of the IRQ pin to a high level. As long as the IRQ pin is low, the IRQ request remains active.
- IRQ vector fetch or software clear. An IRQ vector fetch generates an interrupt acknowledge signal to clear the IRQ latch. Software generates the interrupt acknowledge signal by writing a 1 to ACK in INTSCR. The ACK bit is useful in applications that poll the IRQ pin and require software to clear the IRQ latch. Writing to ACK prior to leaving an interrupt service routine can also prevent spurious interrupts due to noise. Setting ACK does not affect subsequent transitions on the IRQ pin. A falling edge that occurs after writing to ACK latches another interrupt request. If the IRQ mask bit, IMASK, is clear, the CPU loads the program counter with the IRQ vector address.

The IRQ vector fetch or software clear and the return of the $\overline{\text{IRQ}}$ pin to a high level may occur in any order. The interrupt request remains pending as long as the $\overline{\text{IRQ}}$ pin is low. A reset will clear the IRQ latch and the MODE control bit, thereby clearing the interrupt even if the pin stays low.

Use the BIH or BIL instruction to read the logic level on the IRQ pin.

8.3.2 MODE = 0

If the MODE bit is clear, the \overline{IRQ} pin is falling edge sensitive only. With MODE clear, an IRQ vector fetch or software clear immediately clears the IRQ latch.

The IRQF bit in INTSCR can be read to check for pending interrupts. The IRQF bit is not affected by IMASK, which makes it useful in applications where polling is preferred.

NOTE

When using the level-sensitive interrupt trigger, avoid false IRQ interrupts by masking interrupt requests in the interrupt routine.

MC68HC908QY/QT Family Data Sheet, Rev. 6



External Interrupt (IRQ)

8.4 Interrupts

The following IRQ source can generate interrupt requests:

Interrupt flag (IRQF) — The IRQF bit is set when the IRQ pin is asserted based on the IRQ mode.
 The IRQ interrupt mask bit, IMASK, is used to enable or disable IRQ interrupt requests.

8.5 Low-Power Modes

The WAIT and STOP instructions put the MCU in low power-consumption standby modes.

8.5.1 Wait Mode

The IRQ module remains active in wait mode. Clearing IMASK in INTSCR enables IRQ interrupt requests to bring the MCU out of wait mode.

8.5.2 Stop Mode

The IRQ module remains active in stop mode. Clearing IMASK in INTSCR enables IRQ interrupt requests to bring the MCU out of stop mode.

8.6 IRQ Module During Break Interrupts

The system integration module (SIM) controls whether status bits in other modules can be cleared during the break state. The BCFE bit in the break flag control register (BFCR) enables software to clear status bits during the break state. See Chapter 13 System Integration Module (SIM).

To allow software to clear status bits during a break interrupt, write a 1 to the BCFE bit. If a status bit is cleared during the break state, it remains cleared when the MCU exits the break state.

To protect status bits during the break state, write a 0 to BCFE. With BCFE cleared (its default state), software can read and write registers during the break state without affecting status bits. Some status bits have a two-step read/write clearing procedure. If software does the first step on such a bit before the break, the bit cannot change during the break state as long as BCFE is cleared. After the break, doing the second step clears the status bit.

8.7 I/O Signals

The IRQ module shares its pin with the keyboard interrupt, input/output ports, and timer interface modules.

NOTE

When the \overline{IRQ} function is enabled in the CONFIG2 register, the BIH and BIL instructions can be used to read the logic level on the \overline{IRQ} pin. If the \overline{IRQ} function is disabled, these instructions will behave as if the \overline{IRQ} pin is a logic 1, regardless of the actual level on the pin. Conversely, when the \overline{IRQ} function is enabled, bit 2 of the port A data register will always read a 0.

When using the level-sensitive interrupt trigger, avoid false interrupts by masking interrupt requests in the interrupt routine. An internal pullup resistor to V_{DD} is connected to the \overline{IRQ} pin; this can be disabled by setting the IRQPUD bit in the CONFIG2 register (\$001E).

MC68HC908QY/QT Family Data Sheet, Rev. 6



Chapter 10 Low-Voltage Inhibit (LVI)

10.1 Introduction

This section describes the low-voltage inhibit (LVI) module, which monitors the voltage on the V_{DD} pin and can force a reset when the V_{DD} voltage falls below the LVI trip falling voltage, V_{TRIPF} .

10.2 Features

Features of the LVI module include:

- Programmable LVI reset
- Programmable power consumption
- Selectable LVI trip voltage
- Programmable stop mode operation

10.3 Functional Description

Figure 10-1 shows the structure of the LVI module. LVISTOP, LVIPWRD, LVI5OR3, and LVIRSTD are user selectable options found in the configuration register (CONFIG1). See Chapter 5 Configuration Register (CONFIG).

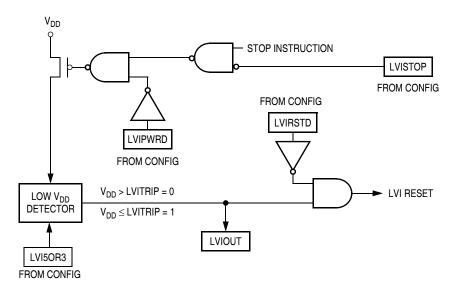


Figure 10-1. LVI Module Block Diagram

The LVI is enabled out of reset. The LVI module contains a bandgap reference circuit and comparator. Clearing the LVI power disable bit, LVIPWRD, enables the LVI to monitor V_{DD} voltage. Clearing the LVI reset disable bit, LVIRSTD, enables the LVI module to generate a reset when V_{DD} falls below a voltage,



again in the SIM and results in the internal bus frequency being one fourth of either the XTALCLK, RCCLK, or INTCLK frequency.

11.5 Low Power Modes

The WAIT and STOP instructions put the MCU in low-power consumption standby modes.

11.5.1 Wait Mode

The WAIT instruction has no effect on the oscillator logic. BUSCLKX2 and BUSCLKX4 continue to drive to the SIM module.

11.5.2 Stop Mode

The STOP instruction disables either the XTALCLK, the RCCLK, or INTCLK output, hence BUSCLKX2 and BUSCLKX4.

11.6 Oscillator During Break Mode

The oscillator continues to drive BUSCLKX2 and BUSCLKX4 when the device enters the break state.

11.7 CONFIG2 Options

Two CONFIG2 register options affect the operation of the oscillator module: OSCOPT1 and OSCOPT0. All CONFIG2 register bits will have a default configuration. Refer to Chapter 5 Configuration Register (CONFIG) for more information on how the CONFIG2 register is used.

Table 11-2 shows how the OSCOPT bits are used to select the oscillator clock source.

 OSCOPT1
 OSCOPT0
 Oscillator Modes

 0
 0
 Internal oscillator

 0
 1
 External oscillator

 1
 0
 External RC

 1
 1
 External crystal

Table 11-2. Oscillator Modes

11.8 Input/Output (I/O) Registers

The oscillator module contains these two registers:

- 1. Oscillator status register (OSCSTAT)
- 2. Oscillator trim register (OSCTRIM)

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MC68HC908QY/QT Family Data Sheet, Rev. 6



13.6.2.1 Interrupt Status Register 1

Address: \$FE04 Bit 7 5 2 Bit 0 Read: 0 IF5 IF4 IF3 0 IF1 0 0 R R R R R R Write: R R 0 0 0 0 0 Reset: 0 0 0 R = Reserved

Figure 13-11. Interrupt Status Register 1 (INT1)

IF1 and IF3-IF5 — Interrupt Flags

These flags indicate the presence of interrupt requests from the sources shown in Table 13-3.

- 1 = Interrupt request present
- 0 = No interrupt request present

Bit 0, 1, 3, and 7 — Always read 0

13.6.2.2 Interrupt Status Register 2

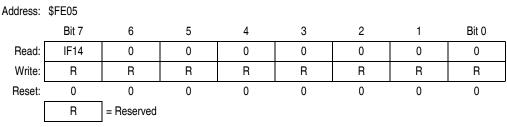


Figure 13-12. Interrupt Status Register 2 (INT2)

IF14 — Interrupt Flags

This flag indicates the presence of interrupt requests from the sources shown in Table 13-3.

- 1 = Interrupt request present
- 0 = No interrupt request present

Bit 0-6 — Always read 0

13.6.2.3 Interrupt Status Register 3

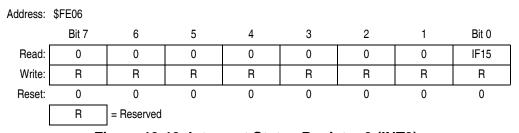


Figure 13-13. Interrupt Status Register 3 (INT3)

IF15 — Interrupt Flags

These flags indicate the presence of interrupt requests from the sources shown in Table 13-3.

- 1 = Interrupt request present
- 0 = No interrupt request present

Bit 1–7 — Always read 0

MC68HC908QY/QT Family Data Sheet, Rev. 6



Timer Interface Module (TIM)

14.4.4.1 Unbuffered PWM Signal Generation

Any output compare channel can generate unbuffered PWM pulses as described in 14.4.4 Pulse Width Modulation (PWM). The pulses are unbuffered because changing the pulse width requires writing the new pulse width value over the old value currently in the TIM channel registers.

An unsynchronized write to the TIM channel registers to change a pulse width value could cause incorrect operation for up to two PWM periods. For example, writing a new value before the counter reaches the old value but after the counter reaches the new value prevents any compare during that PWM period. Also, using a TIM overflow interrupt routine to write a new, smaller pulse width value may cause the compare to be missed. The TIM may pass the new value before it is written.

Use the following methods to synchronize unbuffered changes in the PWM pulse width on channel x:

- When changing to a shorter pulse width, enable channel x output compare interrupts and write the
 new value in the output compare interrupt routine. The output compare interrupt occurs at the end
 of the current pulse. The interrupt routine has until the end of the PWM period to write the new
 value.
- When changing to a longer pulse width, enable TIM overflow interrupts and write the new value in the TIM overflow interrupt routine. The TIM overflow interrupt occurs at the end of the current PWM period. Writing a larger value in an output compare interrupt routine (at the end of the current pulse) could cause two output compares to occur in the same PWM period.

NOTE

In PWM signal generation, do not program the PWM channel to toggle on output compare. Toggling on output compare prevents reliable 0% duty cycle generation and removes the ability of the channel to self-correct in the event of software error or noise. Toggling on output compare also can cause incorrect PWM signal generation when changing the PWM pulse width to a new, much larger value.

14.4.4.2 Buffered PWM Signal Generation

Channels 0 and 1 can be linked to form a buffered PWM channel whose output appears on the TCH0 pin. The TIM channel registers of the linked pair alternately control the pulse width of the output.

Setting the MS0B bit in TIM channel 0 status and control register (TSC0) links channel 0 and channel 1. The TIM channel 0 registers initially control the pulse width on the TCH0 pin. Writing to the TIM channel 1 registers enables the TIM channel 1 registers to synchronously control the pulse width at the beginning of the next PWM period. At each subsequent overflow, the TIM channel registers (0 or 1) that control the pulse width are the ones written to last. TSC0 controls and monitors the buffered PWM function, and TIM channel 1 status and control register (TSC1) is unused. While the MS0B bit is set, the channel 1 pin, TCH1, is available as a general-purpose I/O pin.

NOTE

In buffered PWM signal generation, do not write new pulse width values to the currently active channel registers. User software should track the currently active channel to prevent writing a new value to the active channel. Writing to the active channel registers is the same as generating unbuffered PWM signals.



Table 15-4. WRITE (Write Memory) Command

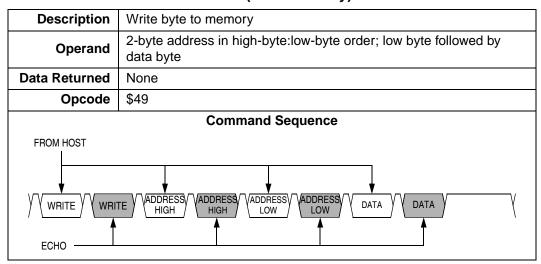


Table 15-5. IREAD (Indexed Read) Command

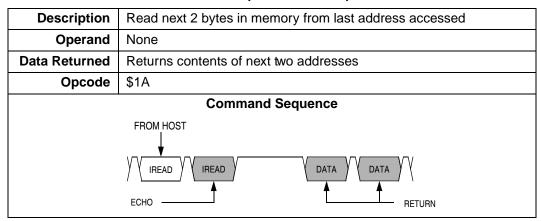
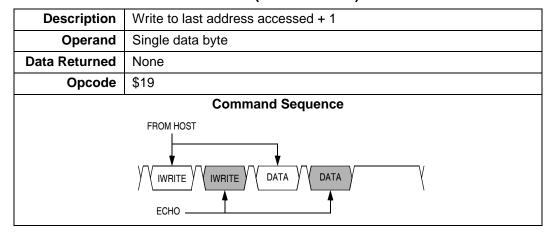


Table 15-6. IWRITE (Indexed Write) Command



A sequence of IREAD or IWRITE commands can access a block of memory sequentially over the full 64-Kbyte memory map.

MC68HC908QY/QT Family Data Sheet, Rev. 6



Chapter 16 Electrical Specifications

16.1 Introduction

This section contains electrical and timing specifications.

16.2 Absolute Maximum Ratings

Maximum ratings are the extreme limits to which the microcontroller unit (MCU) can be exposed without permanently damaging it.

NOTE

This device is not guaranteed to operate properly at the maximum ratings. Refer to 16.5 5-V DC Electrical Characteristics and 16.9 3-V DC Electrical Characteristics for guaranteed operating conditions.

Characteristic ⁽¹⁾	Symbol	Value	Unit
Supply voltage	V _{DD}	-0.3 to +6.0	V
Input voltage	V _{IN}	V_{SS} = 0.3 to V_{DD} + 0.3	V
Mode entry voltage, IRQ pin	V _{TST}	V _{SS} -0.3 to +9.1	V
Maximum current per pin excluding PTA0–PTA5, V_{DD} , and V_{SS}	I	±15	mA
Maximum current for pins PTA0-PTA5	I _{PTA0} —I _{PTA5}	±25	mA
Storage temperature	T _{STG}	-55 to +150	°C
Maximum current out of V _{SS}	I _{MVSS}	100	mA
Maximum current into V _{DD}	I _{MVDD}	100	mA

^{1.} Voltages references to V_{SS}.

NOTE

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum-rated voltages to this high-impedance circuit. For proper operation, it is recommended that V_{IN} and V_{OUT} be constrained to the range $V_{SS} \leq (V_{IN} \text{ or } V_{OUT}) \leq V_{DD}$. Reliability of operation is enhanced if unused inputs are connected to an appropriate logic voltage level (for example, either V_{SS} or V_{DD} .)



Electrical Specifications

16.6 Typical 5-V Output Drive Characteristics

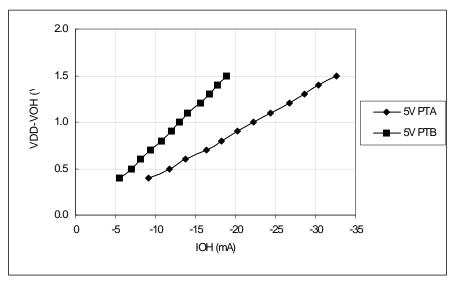


Figure 16-1. Typical 5-Volt Output High Voltage versus Output High Current (25•C)

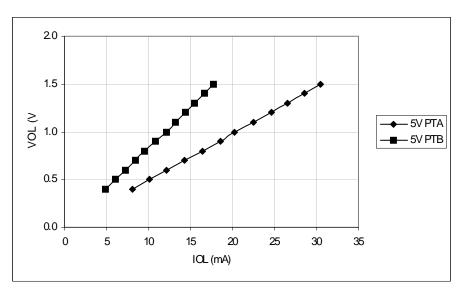


Figure 16-2. Typical 5-Volt Output Low Voltage versus Output Low Current (25•C)



Electrical Specifications

16.10 Typical 3.0-V Output Drive Characteristics

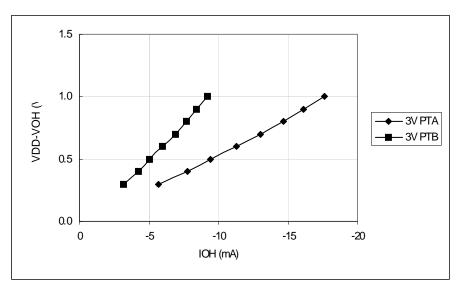


Figure 16-5. Typical 3-Volt Output High Voltage versus Output High Current (25•C)

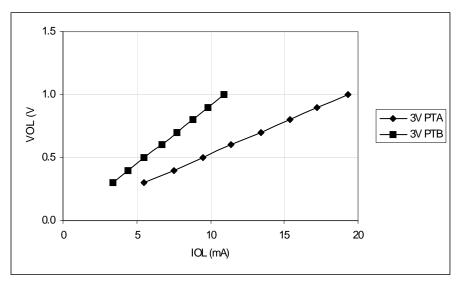


Figure 16-6. Typical 3-Volt Output Low Voltage versus Output Low Current (25•C)



16.16 Memory Characteristics

Characteristic	Symbol	Min	Тур	Max	Unit
RAM data retention voltage	V _{RDR}	1.3	_	_	V
FLASH program bus clock frequency	_	1	_		MHz
FLASH read bus clock frequency	f _{Read} ⁽¹⁾	0	_	8 M	Hz
FLASH page erase time <1 k cycles >1 k cycles	t _{Erase}	0.9 3.6	1 4	1.1 5.5	ms
FLASH mass erase time	t _{MErase}	4	_	_	ms
FLASH PGM/ERASE to HVEN setup time	t _{NVS}	10	_	_	μS
FLASH high-voltage hold time	t _{NVH}	5	_	_	μS
FLASH high-voltage hold time (mass erase)	t _{NVHL}	100	_	_	μS
FLASH program hold time	t _{PGS}	5	_	_	μS
FLASH program time	t _{PROG}	30	_	40	μS
FLASH return to read time	t _{RCV} ⁽²⁾	1	_	_	μS
FLASH cumulative program HV period	t _{HV} ⁽³⁾	_	_	4	ms
FLASH endurance ⁽⁴⁾	_	10 k	100 k	_	Cycles
FLASH data retention time ⁽⁵⁾		15	100	_	Years

- 1. $f_{\mbox{\scriptsize Read}}$ is defined as the frequency range for which the FLASH memory can be read.
- 2. t_{RCV} is defined as the time it needs before the FLASH can be read after turning off the high voltage charge pump, by clearing HVEN to 0.
- 3. t_{HV} is defined as the cumulative high voltage programming time to the same row before next erase. t_{HV} must satisfy this condition: $t_{NVS} + t_{NVH} + t_{PGS} + (t_{PROG} \times 32) \le t_{HV}$ maximum.
- 4. Typical endurance was evaluated for this product family. For additional information on how Freescale defines *Typical Endurance*, please refer to Engineering Bulletin EB619.
- 5. Typical data retention values are based on intrinsic capability of the technology measured at high temperature and de-rated to 25•C using the Arrhenius equation. For additional information on how Freescale defines *Typical Data Retention*, please refer to Engineering Bulletin EB618.





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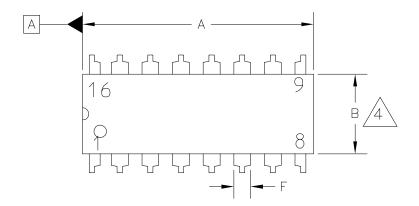
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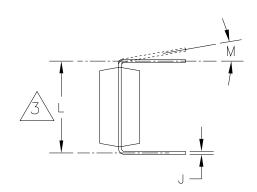
MECHANICAL OUTLINES DICTIONARY

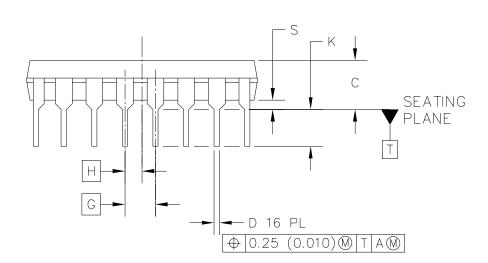
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